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(58) Field of Search

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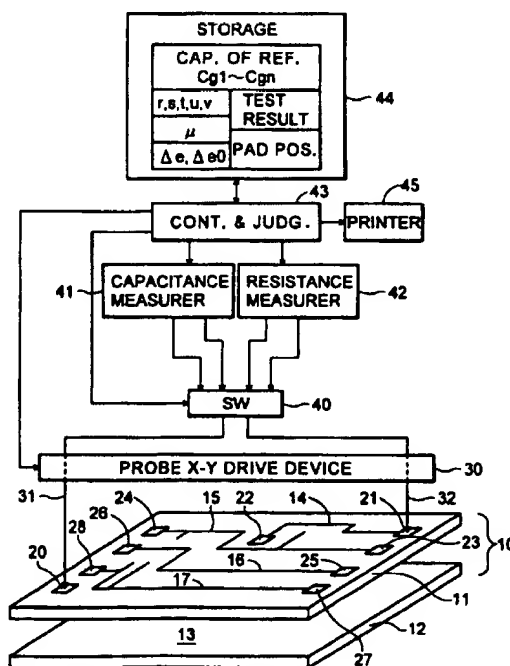
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INT CL<sup>6</sup> G01R 31/02 31/08 31/28

(54) Test/reference capacitance ratio used to assess a conductive pattern on a pcb

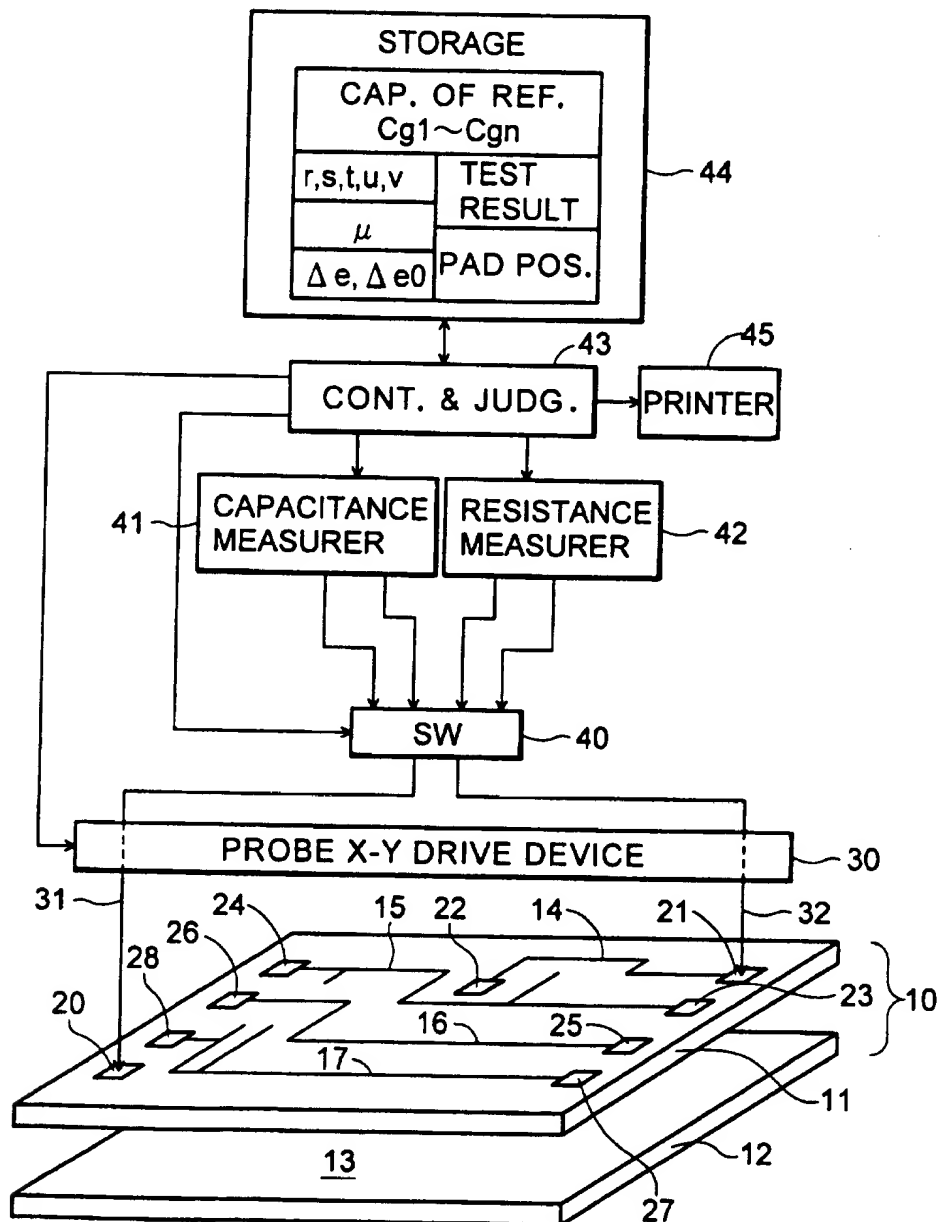
(57) A method or means of electrically testing a wiring pattern 14 - 17 on a printed circuit board (pcb) 10 comprises taking capacitive measurements between certain points on a reference pcb pattern relative to a conductive plane 13, then taking similar measurements made at respective points on a pattern on a pcb under test. The ratio of the measurements of the pcb under test relative to those of the reference pcb is then calculated and used to assess the acceptability of the pattern on the pcb under test. Measurements considered to relate to a faulty pattern may be excluded from the calculation of said ratio. A pattern considered to be faulty may be tested by the resistance measuring method. Tolerance values may be established for the pattern pass or fail assessment.

FIG.1



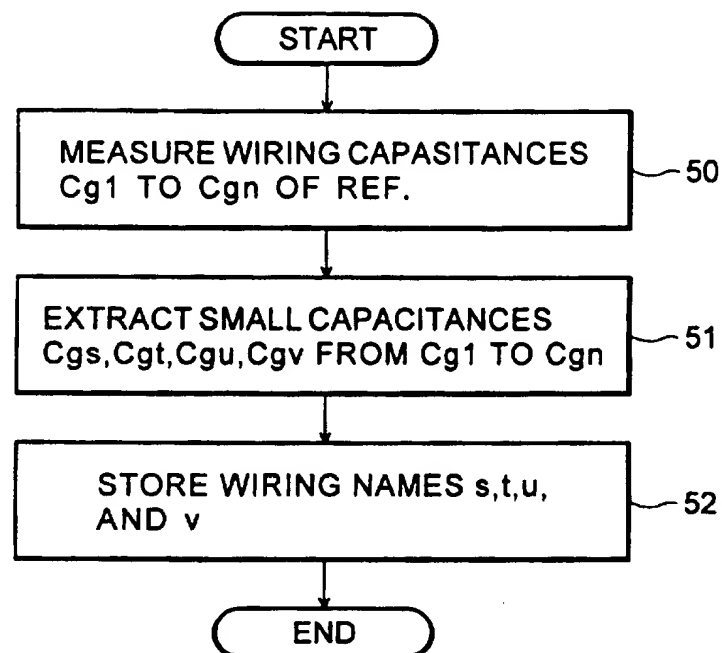
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FIG.1

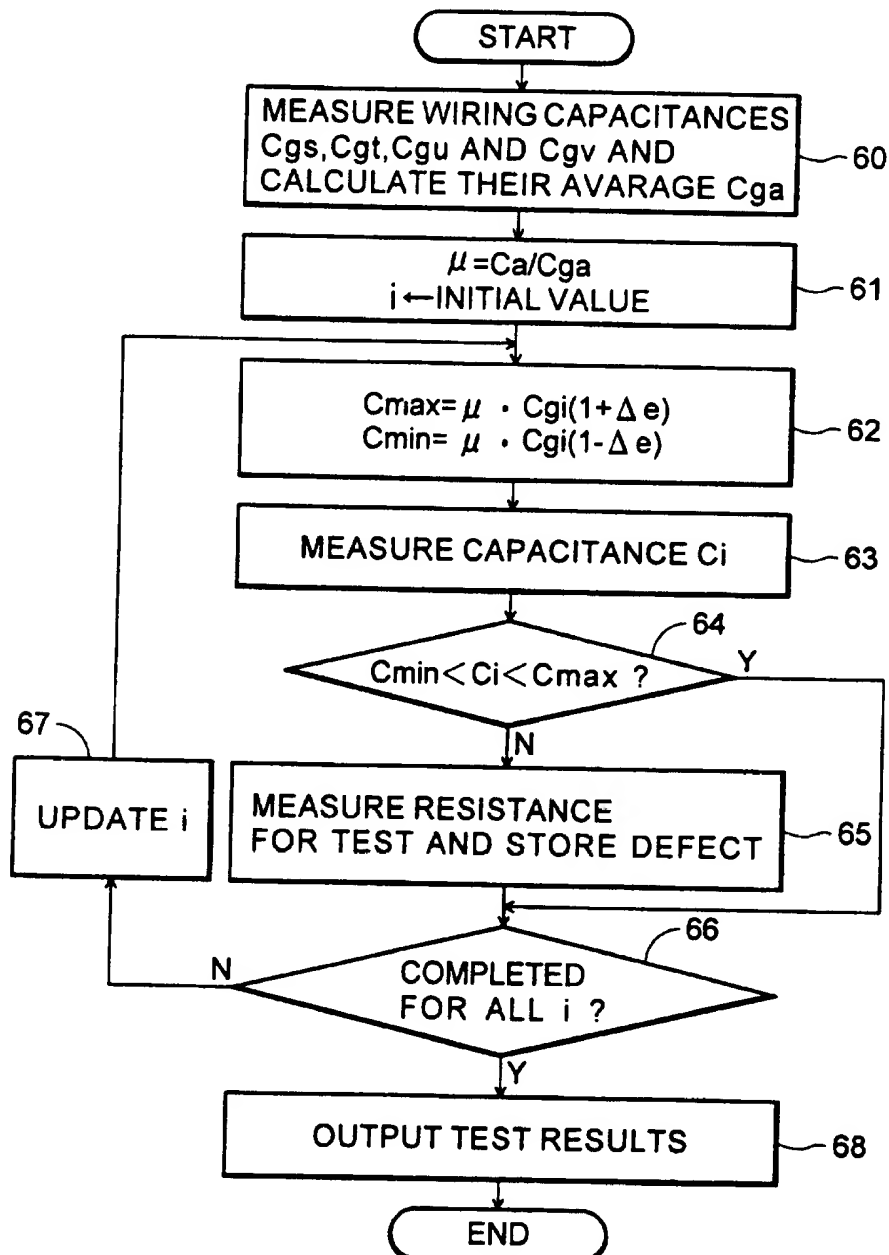


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**FIG.2**



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FIG.3



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METHOD OF AND APPARATUS FOR ELECTRICAL WIRING-PATTERN TEST

The present invention relates to a method of and an